

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.19802	100.0	0.45
Subtotal				0.19802	100	0.45
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.6192	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
Subtotal				1.61936	100	3.68
Lead Frame	Copper alloy	Misc. Phosphor compounds (generic)	7723-14-0	0.0079	0.02	0.01794
	Copper alloy	Iron (Fe)	7439-89-6	0.03158	0.08	0.07178
	Copper alloy	Copper (Cu)	7440-50-8	39.36231	99.7	89.45084
	Pure metal layer	Silver (Ag)	7440-22-4	0.07896	0.2	0.17944
	Subtotal			39.48075	100	89.72
Adhesive	Polymer	Paraffin wax	8002-74-2	0.22002	20.0	0.5
	Polymer	Epoxy resin system		0.08801	8.0	0.2
	Filler	Silver (Ag)	7440-22-4	0.79208	72.0	1.8
Subtotal				1.10011	100	2.5
Mould Compound	Flame retardant	Zinc Borate	138265-88-0	2.56845	4.46	5.8368
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.18297	9.0	11.7783
	Filler	Silica -amorphous-	7631-86-9	17.85245	31.0	40.5697
	Pigment	Carbon black	1333-86-4	0.31098	0.54	0.7067
	Filler	Silicon Dioxide (SiO2)	14808-60-7	31.67371	55.0	71.9785
Subtotal				57.58856	100	130.87
Wire	Pure metal	Copper (Cu)	7440-50-8	0.0132	100.0	0.03
Subtotal				0.0132	100	0.03
Total				100	100	227.25

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.